

CAB

NOTE 3

0.10

DATE 20 MAY 2009

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED
- TERMINAL AND IS MEASURED BETWEEN
- 0.15 AND 0.30 MM FROM TERMINAL TIP. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.80	1.00	
A1	0.00	0.05	
АЗ	0.20 REF		
b	0.25	0.35	
D	4.00 BSC		
D2	2.00	2.20	
Е	4.00 BSC		
E2	2.00	2.20	
е	0.65 BSC		
K	0.20		
Ĺ	0.45	0.65	
11		0.15	

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code

= Assembly Location

= Wafer Lot L Υ = Year W = Work Week = Pb-Free Package

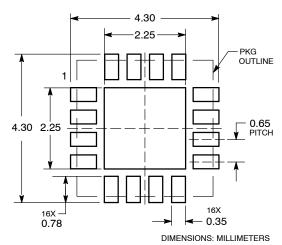
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

MOUNTING FOOTPRINT*

BOTTOM VIEW

е

Ф 0.05 С



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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